Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	214	702/99.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:31
L2	2455	331/25.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:31
L4	0	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) same (temperature or thermal or heat) same (measur$5 or sens$3 or determin$3)) and (temperature same (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) same speed same maximum).clm.	US-PGPUB	OR	ON	2006/01/18 09:41
L5	11	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) and (temperature or thermal or heat) and (measur$5 or sens$3 or determin$3)) and (temperature and (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) and speed same maximum).clm.	US-PGPUB	OR	ON	2006/01/18 09:42
L6	0	1 and 5	US-PGPUB	OR	ON	2006/01/18 09:42
L7	0	2 and 5	US-PGPUB	OR	ON	2006/01/18 09:48
S1	196	702/99.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/18 09:29
S2	13393	((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/10/10 12:35
S3	46	S1 and S2	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:01
S4	4	S3 and ((sort$3 or classify$3 or group$3 or devid$3 or categoriz$3 or separat$3) with (wafer$1 or chip$1 or die$1 or substrate$1 or IC) with temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:11
S5	10	S2 and (maximum adj operating adj frequency)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:17

S6	0	S5 and ((on adj chip) with diode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:17
S7	0	S2 and ((on adj chip) with diode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:18
S8	494430	((on adj chip) diode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:18
S9	0	((on adj chip) with diode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:18
S10	277	((on-chip) with diode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:18
S11	28	S2 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:19
S12	0	S5 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:19
S13	16	S11 and (current with voltage with diode$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:27
S14	0	S13 and (speed near3 categor$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 21:20
S15	16	S2 and ((temperature adj sensitive) with parameter$1 with (wafer$1 or chip$1 or die$1 or (integrated adj circuit$1) or IC))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:56
S16	57413	(appleyard with jennifer) or (carlson with troy) or (forbes with joseph) or (percy with dean) or (rohrer with norman) or (tanona with william) or (international adj business adj machines)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 09:58

S17	7121	TEMPERATURE and FREQUENCY and MEASUREMENT and SPEED and SORT$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:11
S18	89	S16 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:06
S19	1430	TEMPERATURE and FREQUENCY and MEASUREMENT and SPEED and SORT$3 and (IC or (integrat$2 adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:12
S20	17	S16 and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:11
S21	1006	TEMPERATURE and FREQUENCY and MEASUREMENT and SPEED and SORT$3 and (IC or (integrat$2 adj circuit)) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:32
S22	14	S16 and S21	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/15 10:14
S23	0	("2005/0026476").URPN.	USPAT	OR	OFF	2005/04/15 10:14
S24	2	("2002/0171133").URPN.	USPAT	OR	OFF	2005/04/15 10:15
S25	0	("2001/0013111").URPN.	USPAT	OR	OFF	2005/04/15 10:15
S26	71	("20030071348" | "20030075795" | "3842189" | "4320438" | "4423401" | "4758927" | "5121298" | "5152695" | "5166774" | "5280139" | "5385477" | "5416429" | "5476211" | "5532612" | "5613861" | "5756021" | "5764070" | "5772451" | "5786701" | "5806181" | "5820014" | "5829128" | "5832601" | "5847572" | "5848685" | "5852871" | "5864946" | "5878486" | "5884398" | "5897326" | "5905305" | "5912046" | "5917707" | "5944537" | "5974662" | "5983493" | "5994152" | "5994222" | "5994781" | "5998228" | "5998864" | "6001671" | "6002168" | "6007349" | "6012224" | "6020220" | "6023103" | "6029344" | "6030856" | "6032356" | "6033935" | "6042712" | "6043563" | "6044548" | "6045396" | "6045655" | "6046076" | "6049972" | "6049976" | "6050829" | "6054337" | "6054756" | "6063648" | "6064213" | "6075289" | "6078186" | "6080603" | "6080605" | "6080932" | "6081035" | "6544814").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:16
S27	1	("6791171").URPN.	USPAT	OR	OFF	2005/04/15 10:17

S28	6	("5061652" | "6021050" | "6108212" | "6111305" | "6133615" | "6210537").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:18
S29	0	("6720595").URPN.	USPAT	OR	OFF	2005/04/15 10:18
S30	20	("4049980" | "4229667" | "4263519" | "4670670" | "4695745" | "5103277" | "5397934" | "5612645" | "5748016" | "5753958" | "5834966" | "5892260" | "5898618" | "5917365" | "5939934" | "5943246" | "6215348" | "6301133" | "6301168" | "6342816").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:19
S31	0	("6487701").URPN.	USPAT	OR	OFF	2005/04/15 10:19
S32	23	("3794766" | "4620302" | "4796259" | "4893072" | "5003256" | "5039939" | "5206861" | "5212443" | "5235566" | "5444406" | "5621739" | "5651013" | "5689539" | "5754063" | "5790560" | "5880612" | "5923676" | "5936977" | "5959487" | "5982681" | "5996097" | "6046620" | "6125461").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:20
S33	2	("6415402").URPN.	USPAT	OR	OFF	2005/04/15 10:20
S34	13	("4760265" | "5430305" | "5440566" | "5469051" | "5502001" | "5502390" | "5568055" | "5594248" | "5747999" | "5821759" | "6078183" | "6141093" | "6242923").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:21
S35	0	("6400128").URPN.	USPAT	OR	OFF	2005/04/15 10:22
S36	19	("4605893" | "4760265" | "5162742" | "5351001" | "5430396" | "5440565" | "5469051" | "5489851" | "5502001" | "5502390" | "5561696" | "5568055" | "5570027" | "5594248" | "5747999" | "5804980" | "5821759" | "5841788" | "6078183").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:22
S37	2	("6236196").URPN.	USPAT	OR	OFF	2005/04/15 10:23
S38	19	("3794766" | "4620302" | "4796259" | "4893072" | "5003256" | "5039939" | "5206861" | "5212443" | "5235566" | "5444406" | "5621739" | "5651013" | "5880612" | "5923676" | "5936977" | "5959487" | "5982681" | "5996097" | "6046620").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:23
S39	5	("6219813").URPN.	USPAT	OR	OFF	2005/04/15 10:24
S40	5	("4363002" | "4743857" | "4795985" | "4821297" | "4926447").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:24
S41	13	("5663991").URPN.	USPAT	OR	OFF	2005/04/15 10:25

| S42 | 793 | ("0033189" \| "2418127" \| "2510046" \| "2511085" \| "2563448" \| "2573349" \| "2619530" \| "2731197" \| "2769023" \| "2788387" \| "2864885" \| "2866962" \| "2875270" \| "2892882" \| "2972008" \| "3016091" \| "3071642" \| "3071649" \| "3107274" \| "3133986" \| "3213201" \| "3238297" \| "3244806" \| "3251051" \| "3304416" \| "3336437" \| "3363250" \| "3440427" \| "3470309" \| "3478164" \| "3478166" \| "3485946" \| "3493674" \| "3500327" \| "3526843" \| "3531583" \| "3531586" \| "3536833" \| "3546684" \| "3560936" \| "3564509" \| "3569937" \| "3573747" \| "3576391" \| "3584142" \| "3601528" \| "3602891" \| "3609697" \| "3639686" \| "3649749" \| "3651261" \| "3651471" \| "3657699" \| "3659046" \| "3666888" \| "3668307" \| "3669307" \| "3683111" \| "3684823" \| "3693090" \| "3696297" \| "3703684" \| "3712956" \| "3723637" \| "3725672" \| "3726992" \| "3728480" \| "3729581" \| "3731197" \| "3733430" \| "3733431" \| "3736369" \| "3743767" \| "3746799" \| "3749845" \| "3752908" \| "3755624" \| "3757225" \| "3769579" \| "3773977" \| "3773979" \| "3777053" \| "3789131" \| "3789137" \| "3790700" \| "3794922" \| "3795763" \| "3798359" \| "3798610" \| "3803491" \| "3806814" \| "3813482" \| "3819852" \| "3824332" \| "3824467" \| "3825893" \| "3826863" \| "3833757" \| "3835387" \| "3836888" \| "3842196" \| "3845391" \| "3848082" \| "3848193" \| "3849729" \| "3859458" \| "3859596" \| "3875329" \| "3882289" \| "3882392" \| "3885089" \| "3886302" \| "3886454" \| "3889054" \| "3890461" \| "3891792" \| "3893031" \| "3894176" \| "3894177" \| "3896262" \| "3896266" \| "3899633" \| "3906450" \| "3911216" \| "3914534").PN. OR ("3916091" \| "3919462" \| "3921151" \| "3924059" \| "3924187" \| "3927250" \| "3934079" \| "3936593" \| "3936594" \| "3936595" \| "3936868" \| "3943447" \| "3947624" \| "3947882" \| "3947972" \| "3949313" \| "3950607" \| "3950618" \| "3956615" \| "3958081" \| "3961137" \| "3970790" \| "3973206" \| "3975583" \| "3975585" \| "3978449" \| "3982064" \| "3982065" \| "3984637" \| "3987397" \| "3987398" \| "3988528" \| "3990012" \| "3990050" \| "3996583" \| "3996586" \| "3997718" \| "4004085" \| "4008369" \| "4013875" \| "4015286" \| "4016361" \| "4017697" \| "4019201" \| "4020419" \| "4024574" \| "4024575" \| "4025851" \| "4025947" \| "4025948" \| "4026555" \| "4027267" \| "4027331" \| "4031548" \| "4032972" \| "4042958" \| "4044376" \| "4045814" \| "4048562" \| "4048619" \| "4049906" \| "4052719" \| "4052737" \| "4054911" \| "4055848" \| "4057829" \| "4058830" \| "4069490" \| "4068264" \| "4070693" \| "4074315" \| "4075660" \| "4078316" \| "4079419" \| "4081612" \| "4081753" \| "4081754" \| "4081831" \| "4081832" \| | US-PGPUB; USPAT; USOCR | OR | OFF | 2005/04/15 10:28 |

S43	0	S21 and S42	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:27
S44	56	S42 and temperature	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:32
S45	21	S44 and (TEMPERATURE and (IC or (integrat$2 adj circuit)) and chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/15 10:34
S46	27	("5887243").URPN.	USPAT	OR	OFF	2005/04/15 10:35
S47	27	("5887243").URPN.	USPAT	OR	OFF	2005/04/15 10:36
S48	1	("4631421").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:37
S49	10	("4720670").URPN.	USPAT	OR	OFF	2005/04/15 10:37
S50	18	("3602799" | "3736477" | "3743850" | "3754181" | "3758791" | "3778646" | "3794861" | "3803471" | "3808468" | "3978473" | "4004164" | "4029974" | "4100431" | "4145621" | "4160934" | "4172992" | "4287437" | "Re29619").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/15 10:38
S51	6	("4383216").URPN.	USPAT	OR	OFF	2005/04/15 10:38
S52	1	("6002280").URPN.	USPAT	OR	OFF	2005/04/15 10:38
S53	3	"6515548".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 11:26
S55	2	"20030208286"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 11:30
S56	630	702/130.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:50
S57	175	702/132.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:50
S58	280	702/136.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:50
S59	747	702/117.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:51

S60	608	702/108.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:51
S61	13529	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 10:59
S62	93	S56 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:49
S63	47	S57 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:50
S64	15	S58 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:50
S65	14	S59 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:50
S66	2	S60 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:59
S67	2	"6871151".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 18:05
S68	2595	331/25.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/10 12:34
S69	369	700/31.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/10 12:34

S70	14511	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/10 12:35
S72	6	S68 and S70	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/10 12:36
S73	5	S69 and S70	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/12 14:31
S74	2	"6870084".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/17 14:49
S75	2	"20050076770"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/17 14:50
S76	4223	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4))	US-PGPUB	OR	OFF	2005/12/19 11:27
S77	1279	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) and speed and maximum	US-PGPUB	OR	OFF	2005/12/19 11:31
S78	24	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) same speed same maximum	US-PGPUB	OR	OFF	2005/12/19 12:50
S79	0	((((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) same speed same maximum).clm.	US-PGPUB	OR	OFF	2005/12/19 11:37

S80	6	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) and speed and maximum).clm.	US-PGPUB	OR	OFF	2005/12/19 11:32
S81	22	702/99.ccls.	US-PGPUB	OR	OFF	2005/12/19 11:33
S82	104	331/25.ccls.	US-PGPUB	OR	OFF	2005/12/19 11:33
S83	1	S80 and S81	US-PGPUB	OR	OFF	2005/12/19 11:34
S84	0	S80 and S82	US-PGPUB	OR	OFF	2005/12/19 11:34
S85	180	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) same speed same maximum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:39
S86	29	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) with speed with maximum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:41
S87	29	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) with speed with (maximum or Tmaxfor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:52
S88	99	("5834841" "5973401" "4356379" "5365129" "5546041" "5795063" "5927853" "5977813" "4883992" "5412992" "6222375" "6222375" "6412977" "6476597" "5751196" "5640122" "4952865" "4972101" "5491610" "5689203" "5731517" "6055252" "4473793" "4894562" "5798692" "5831472" "5909404" "5917363" "5986281" "6195030" "6210085" "6210085" "6249002" "4323325" "4338571" "4361538" "4381602" "4470190" "4549150" "4625128" "4779226" "4845649" "4849661" "4849686" "4937476" "4949274" "5007478" "5021750" "5389340" "5406285").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:52
S89	646	324/601.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:55
S90	174	326/71.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:53

S91	863	327/512.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:58
S92	1467	331/111.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:53
S93	2613	341/144.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:54
S94	510	374/43.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:54
S95	409	409/135.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:54
S96	0	S85 and S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:57
S97	0	S85 and S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:58
S98	1	S85 and S91	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:56
S99	0	S85 and S92	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59

S100	0	S85 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S101	0	S85 and S94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S102	0	S85 and S95	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S103	1	S77 and S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:58
S105	0	S77 and S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:58
S106	0	S77 and S91	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S107	0	S77 and S92	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S108	2	S77 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59
S109	1	S77 and S94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/19 11:59

S110	0	S77 and S95	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/19 11:59
S111	24	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) with (temperature or thermal or heat) with (measur$5 or sens$3 or determin$3)) and (temperature with (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) same speed same maximum	US-PGPUB	OR	ON	2006/01/18 09:33
S112	0	(((((semi adj conductor) or semiconductor) or wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or substrate$1) same (temperature or thermal or heat) same (measur$5 or sens$3 or determin$3)) and (temperature same (compensat$3 or correct$3 or offset or calibrat$3 or adjust$4)) same speed same maximum).clm.	US-PGPUB	OR	ON	2005/12/19 12:51
S113	32	(wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with test$3 with (temperature or thermal or heat) with (maximum or threshold or limit) same (measur$5 or determin$3 or calculat$3 or comput$3 or obtain$3 or detect$3 or decid$3 or ascertain$3 or estimat$3 or evaluat$3) with (speed or performance or rate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 11:54
S114	723	(wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with sort$3 with (speed or performance or rate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 12:07
S115	104	S114 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) same test$3 with (temperature or thermal or heat) same (speed or performance or rate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 11:55
S116	97	S114 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with test$3 with (temperature or thermal or heat) same (speed or performance or rate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 11:55
S117	70	S114 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with test$3 with (temperature or thermal or heat) with (speed or performance or rate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 11:55
S118	1	S117 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with sort$3 with percentage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 12:08

S11 9	0	S117 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with sort$3 with fraction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/20 15:41
S12 0	24	S117 and (wafer$1 or (integrated adj circuit$1) or chip$1 or die$1 or IC) with sort$3 with (category or group)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/20 12:09
S12 1	3	("6515548").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/20 14:33